

Product End-of-Life Disassembly Instructions
Product Category: Storage
Marketing Name / Model
[List multiple models if applicable.]

HPE Primera 6xx Storage Drive Expansion Enclosures (600, 630, 650, 670)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2012/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Power supply =1 ea Midplanes =1 ea Temp sensor boards = 1 ea	1 per enclosure 1 per power supply 1 per temp sensor
Batteries	All types including standard alkaline and lithium coin or button style batteries :	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords	PCV insulation on external power cords.	0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Item Description	Notes	Quantity of items included in product
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips screw driver	#0, #1, #2
Pry Bar	Small
Torx Driver	T10, T15
Grinder or drill for rivet removal	small

3.0 Product Disassembly Process

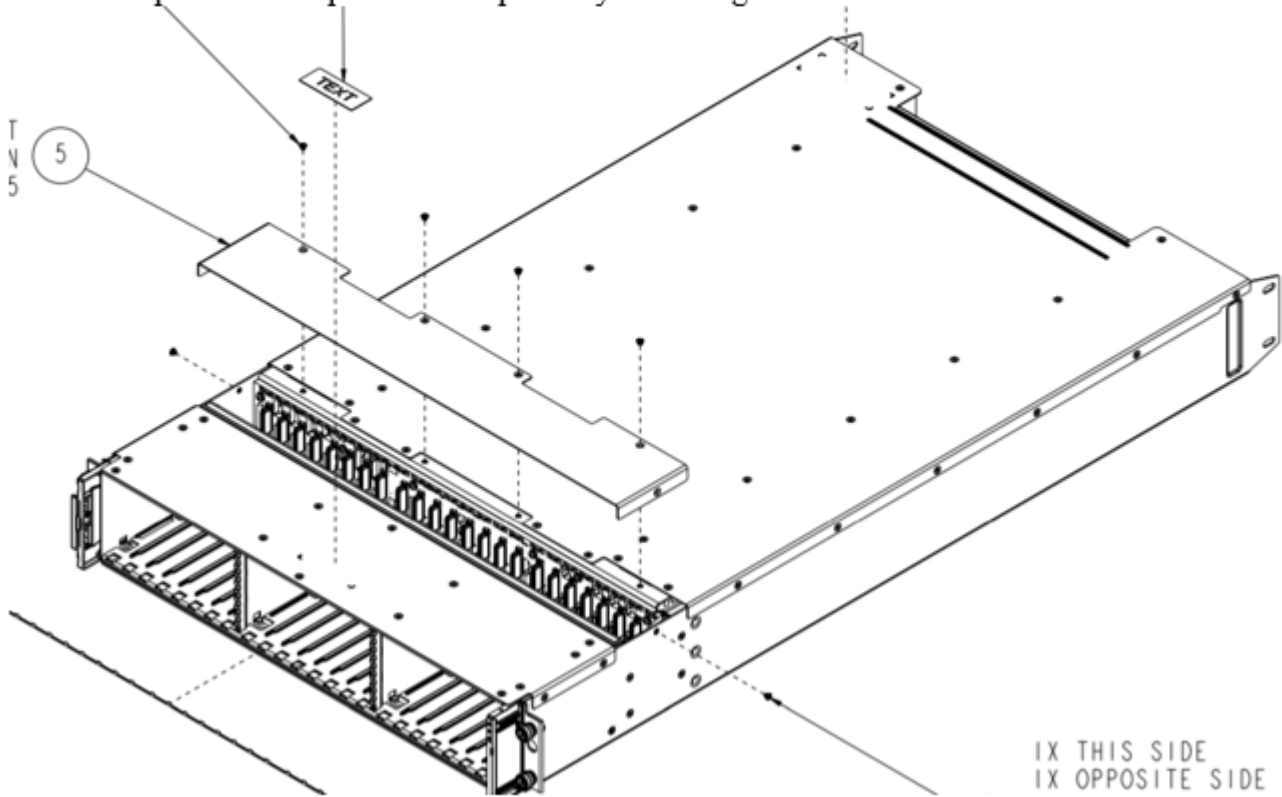
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Power Cooling Modules from the rear of the enclosure. Special disassembly process is required for the PCM modules and will be provided when available.
2. Remove Sheetmetal top cover exposing the Midplane.
3. Remove screws securing the Midplane.
4. Remove temp sensor cable and Midplane.
5. Remove temp sensor board

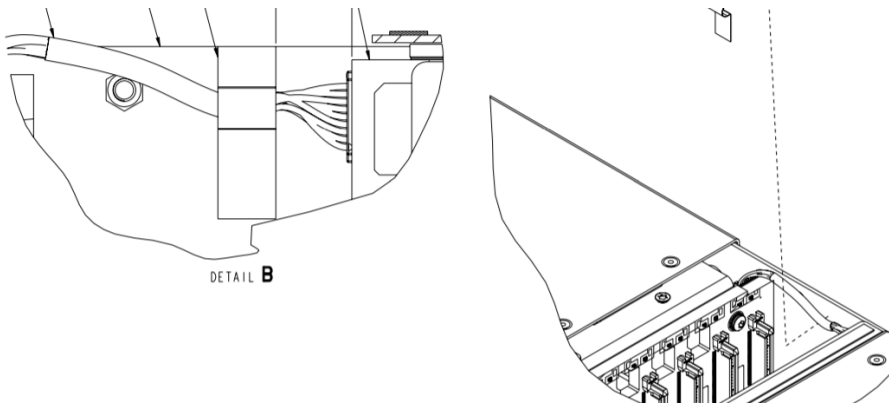
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

SFF enclosure process

Remove top cover to expose the midplane by removing all screws. .

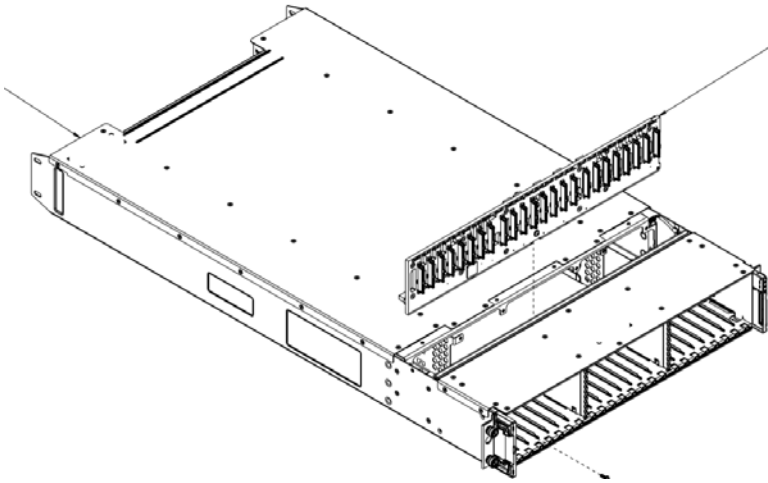
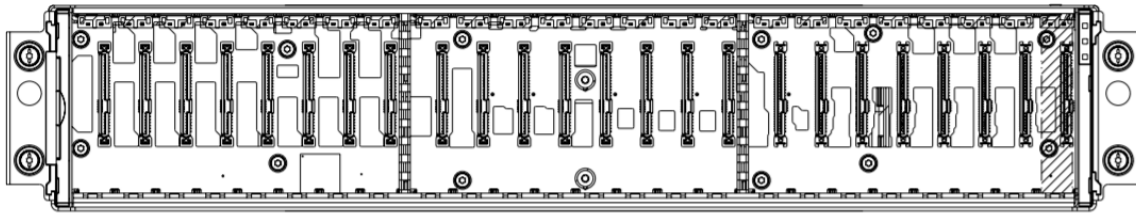


Remove temp sensor cable from the midplane.

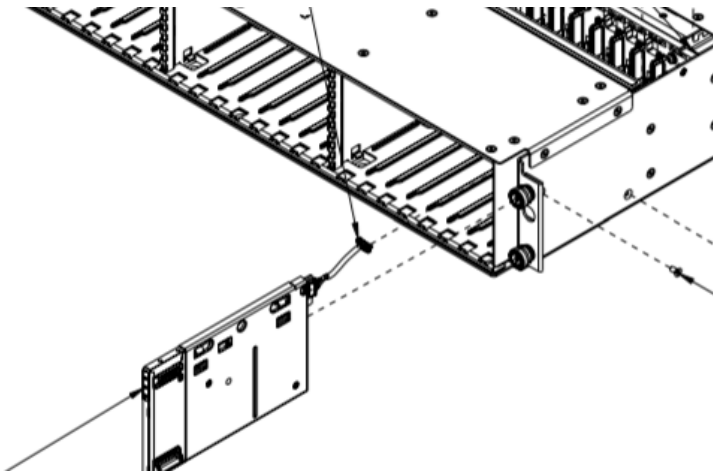


Remove all screws from midplane and lift midplane and up and out from the enclosure.

Small Form Factor N9Z50A shown

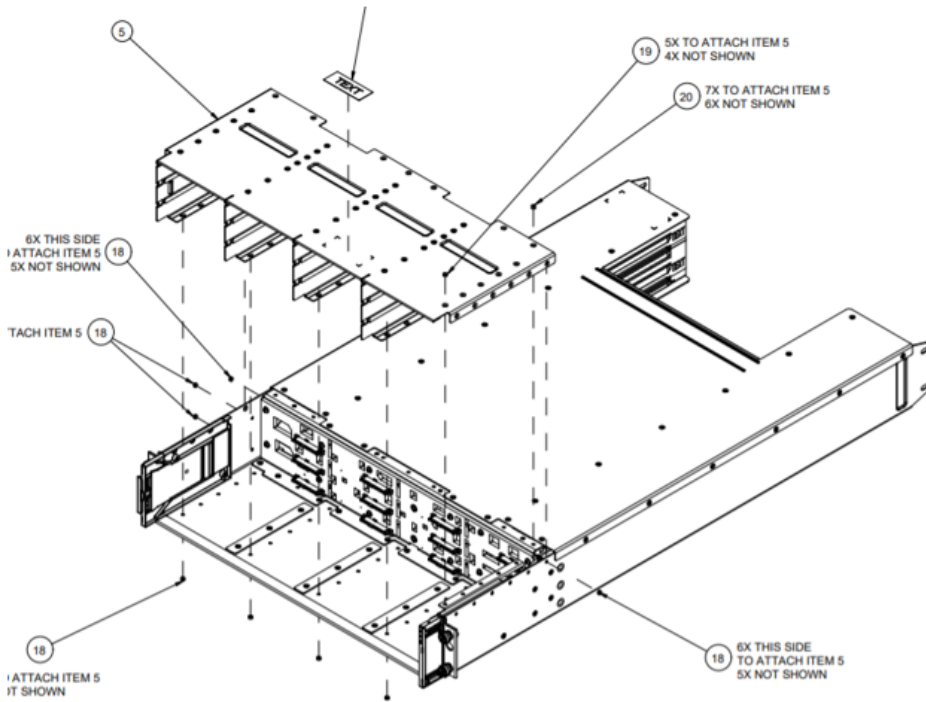


Remove temp sensor board from enclosure. Screws fasten the board to the enclosure from the outside.

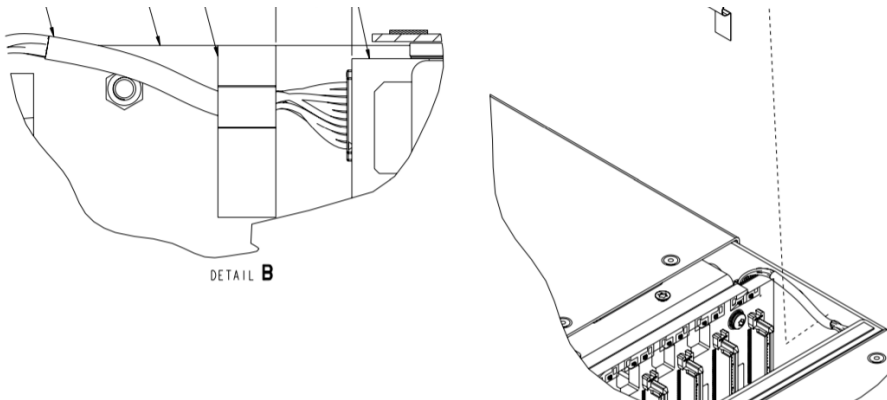


LFF enclosure process

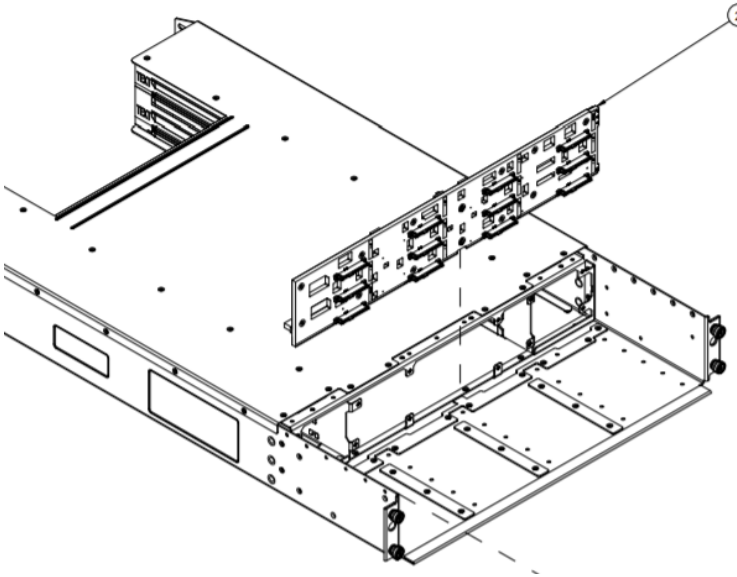
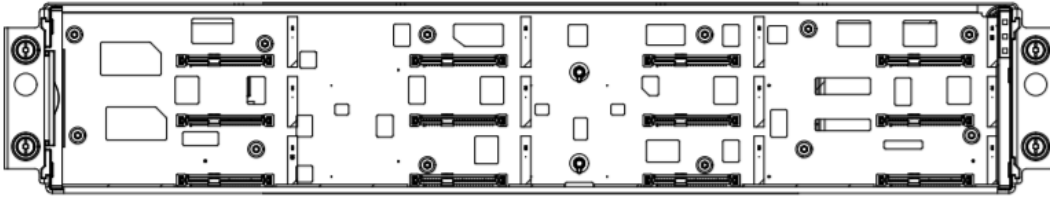
The LFF enclosure is riveted together. All rivets must be removed from front cage top, sides and bottom as shown. Drill or grinder is required for rivet removal. Also, a prybar is recommended.



Remove temp sensor cable from the midplane.



Remove all screws from midplane and lift midplane and up and out from the enclosure.



Remove temp sensor board from enclosure. Screws fasten the board to the enclosure from the outside.

